

Title (en)
MATERIAL FOR INSULATING SUBSTRATE, PRINTED BOARD, LAMINATE, COPPER FOIL WITH RESIN, COPPER-CLAD LAMINATE, POLYIMIDE FILM, FILM FOR TAB, AND PREPREG

Title (de)
MATERIAL FÜR ISOLIERENDES SUBSTRAT, LEITERPLATTE, LAMINAT, KUPFERFOLIE MIT HARZ, KUPFERUMMANTELTES LAMINAT, POLYIMIDFOLIE, FOLIE FÜR TABS UND PREPREGS

Title (fr)
MATERIAU DE SUBSTRATS ISOLANTS, STRATIFIE POUR CARTE A CIRCUIT IMPRIME, FEUILLE DE CUIVRE AVEC RESINE, STRATIFIE A REVETEMENT DE CUIVRE, FILM POLYIMIDE, FILM POUR TAB, ET PREIMPREGNE

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Abstract (en)
[origin: EP1350815A1] It is an object of the invention to provide a material for insulating substrate, a printed board, a laminate, copper foil with resin, a copper-clad laminate, a polyimide film, a film for TAB and a prepreg, which are excellent in physical properties, dimensional stability, heat resistance, flame retardancy etc. and exhibit an excellent flame retardant effect particularly by a shape retention effect at the time of combustion <?? >The invention provides a material for insulating substrate, comprising 100 parts by weight of a thermoplastic resin or a mixture of a thermoplastic resin and a thermosetting resin and 0.1 to 100 parts by weight of a layered silicate.

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Citation (search report)

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